

SC180N75ZTF

Silicon Carbide MOSFET 750V, 180mΩ, 19A



重庆平伟半导体股份有限公司

Features

- 0 V turn-off gate voltage can be applied
- High Blocking Voltage with Low RDS(on)
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Qualified according to JEDEC criteria

Applications

- Lighting
- Telecom and UPS
- PWM stages for e.g. PC Silverbox, Adapter, LCD & PDP TV



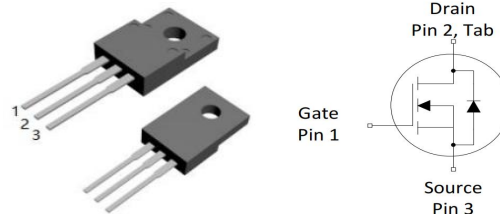
100% DVDS Tested

**100%
Avalanche Tested**

Product Summary

V_{DS}	750V
$R_{DS(on)}$ typ.	180mΩ
I_D	19A

TO-220TF-3L



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
SC180N75ZTF	SC180N75ZTF	TO-220TF-3L	N/A	N/A	N/A	50

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	750	V
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$ (Silicon limit)	I_D	19 13	A
Pulsed drain current ($T_C = 25^\circ\text{C}$)	$I_{D \text{ pulse}}$	57	A
Avalanche energy, single pulse ($L=5\text{mH}$)	E_{AS}	16	mJ
Gate-Source voltage,max.transient voltage	$V_{GS\text{max}}$	-8/+22	V
Recommended operating values	$V_{GS\text{sop}}$	0/+18	V
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	30	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+175	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	R_{thJC}	-	1.33	5.0	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	R_{thJA}	-	-	55	°C/W	1 inch ² , 2oz single copper FR-4 PCB.

Electrical Characteristic (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	750	-	-	V	$V_{GS}=0V, I_D=100\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.5	3.5	4.5	V	$V_{DS}=V_{GS}, I_D=6mA$
Zero gate voltage drain current	I_{DSS}	-	1	10	μA	$V_{DS}=750V, V_{GS}=0V$ $T_j=25^\circ C$
		-	-	100		$T_j=175^\circ C$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{GS}=22V, V_{DS}=0V$
		-	-	-100	nA	$V_{GS}=-8V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	180	240	mΩ	$V_{GS}=15V, I_D=10A$
Drain-source on-state resistance	$R_{DS(on)}$	-	130	185	mΩ	$V_{GS}=18V, I_D=10A$
Transconductance	g_{fs}	-	6.5	-	S	$V_{DS}=20V, I_D=10A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	503	-	pF	$V_{GS}=0V, V_{DS}=400V,$ $f=1MHz$
Output Capacitance	C_{oss}	-	42	-		
Reverse Transfer Capacitance	C_{rss}	-	4	-		
Gate Total Charge	Q_G	-	17	-	nC	$V_{DS}=400V, I_D=10A$ $, V_{GS}=0V/15V$
Gate-Source charge	Q_{gs}	-	5	-		
Gate-Drain charge	Q_{gd}	-	8	-		
Turn-on delay time	$t_{d(on)}$	-	12	-	ns	$V_{GS}=0/18V, V_{DD}=400V,$ $R_G=5\Omega, I_D=10A$
Rise time	t_r	-	13	-		
Turn-off delay time	$t_{d(off)}$	-	22	-		
Fall time	t_f	-	7	-		
Gate resistance	R_G	-	3.0	-	Ω	$V_{GS}=0V, f=1MHz$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	4.2	-	V	$V_{GS}=0V, I_{SD}=10A$ $T_j=25^{\circ}C$
		-	3.7	-		$T_j=175^{\circ}C$
Body Diode Continuous Forward Current	I_S	-	-	18	A	$T_C = 25^{\circ}C$
		-	-	13	A	$T_C = 100^{\circ}C$
Body Diode Reverse Recovery Time	t_{rr}	-	23	-	ns	$V_{GS}=-5V, I_{SD}=10A,$ $V_R=400V$ $di/dt=1000A/us$
Body Diode Reverse Recovery Charge	Q_{rr}	-	88	-	nC	
Peak Reverse Recovery Current	I_{RRM}	-	5	-	A	

Typical Performance Characteristics

Fig 1: Output Characteristics $T_j=25^\circ\text{C}$

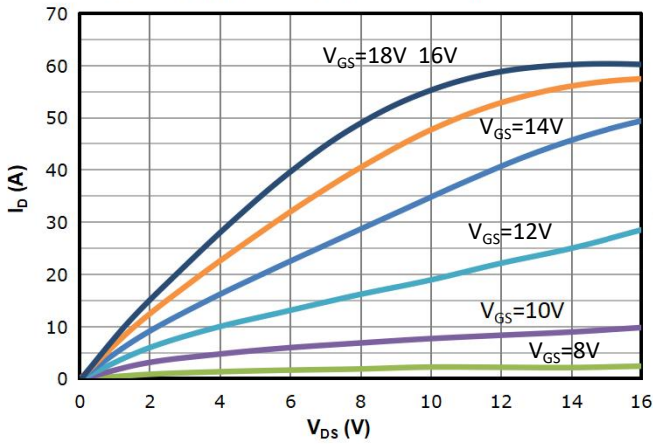


Fig 2: Output Characteristics $T_j=175^\circ\text{C}$

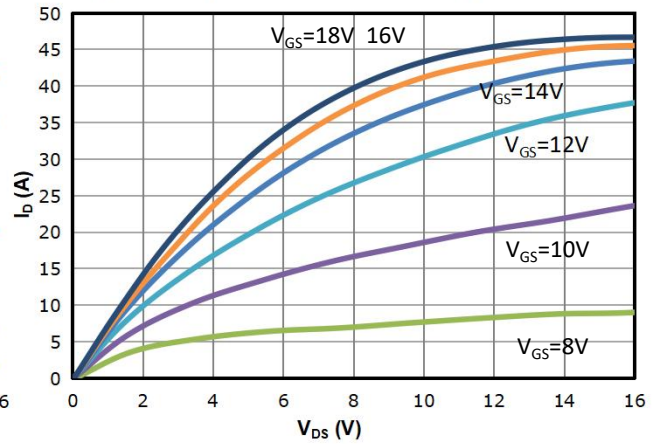


Fig 3: Transfer Characteristics

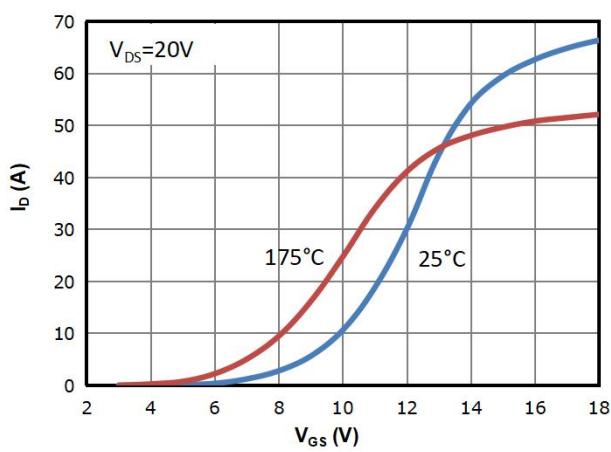


Fig 4: $R_{DS(on)}$ vs Drain Current and Gate Voltage

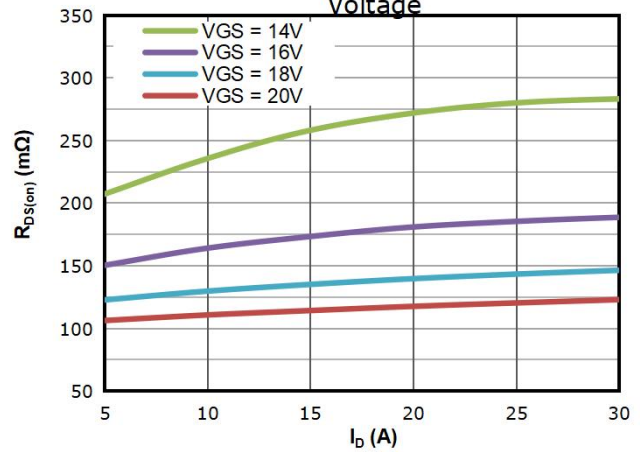


Fig 5: $R_{DS(on)}$ vs. Temperature

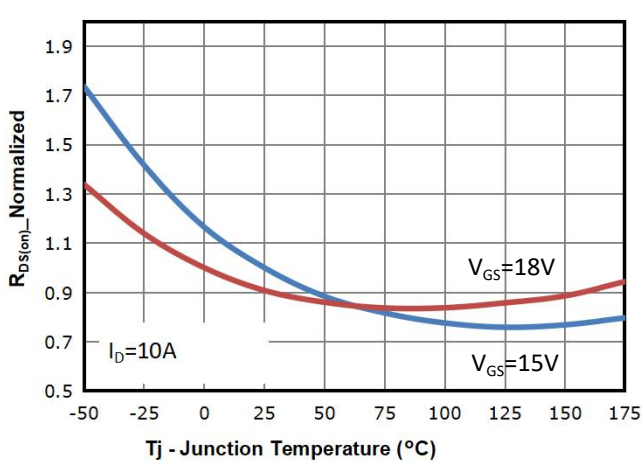


Fig 6: $V_{GS(th)}$ vs. Temperature

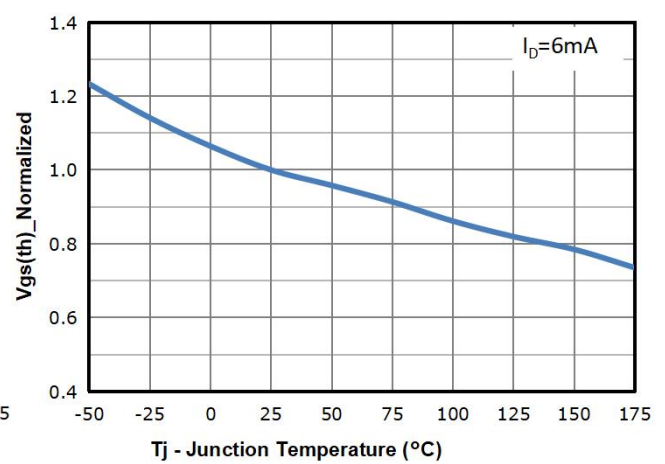


Fig 7: BVdss vs. Temperature

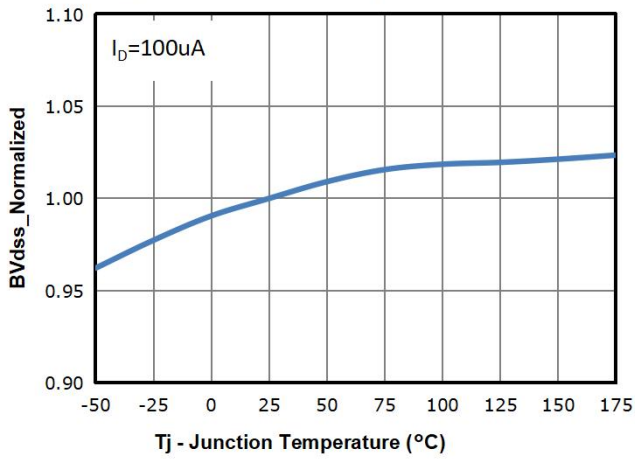


Fig 8: Capacitance Characteristics

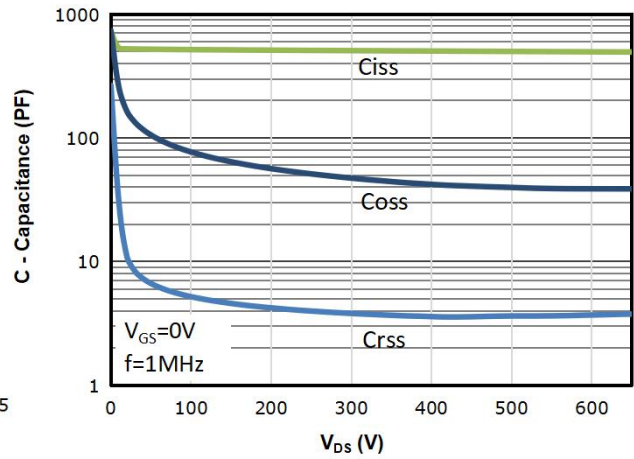


Fig 9: Gate Charge Characteristics

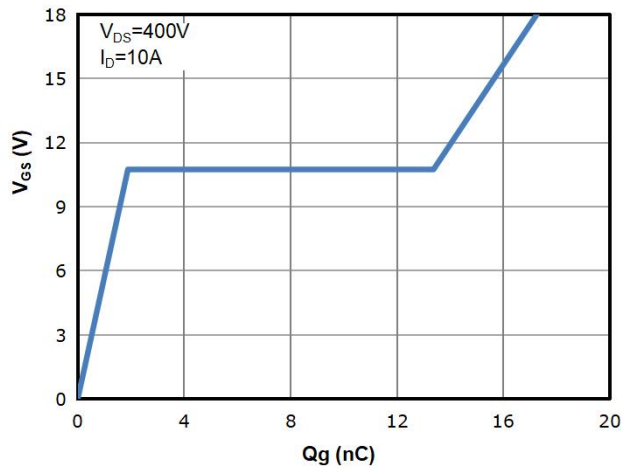


Fig 10: Body-diode Forward Characteristics

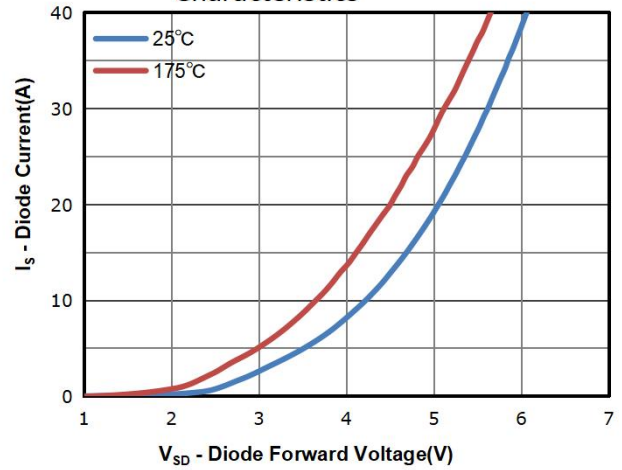


Fig 11: Power Dissipation

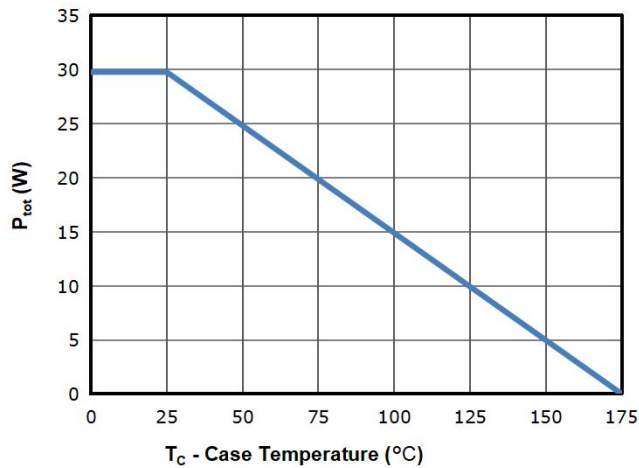


Fig 12: Drain Current Derating

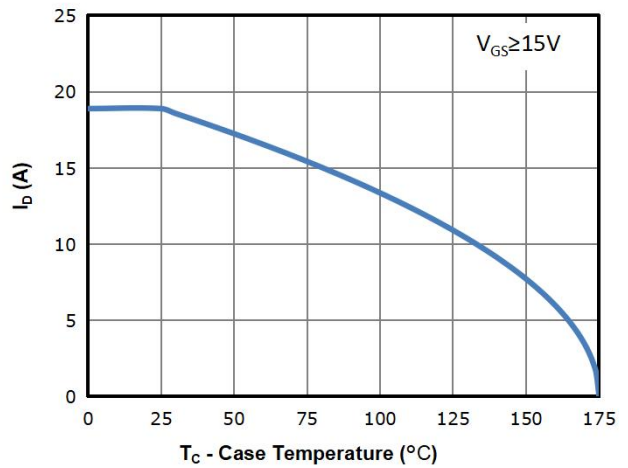




Fig 13: Safe Operating Area

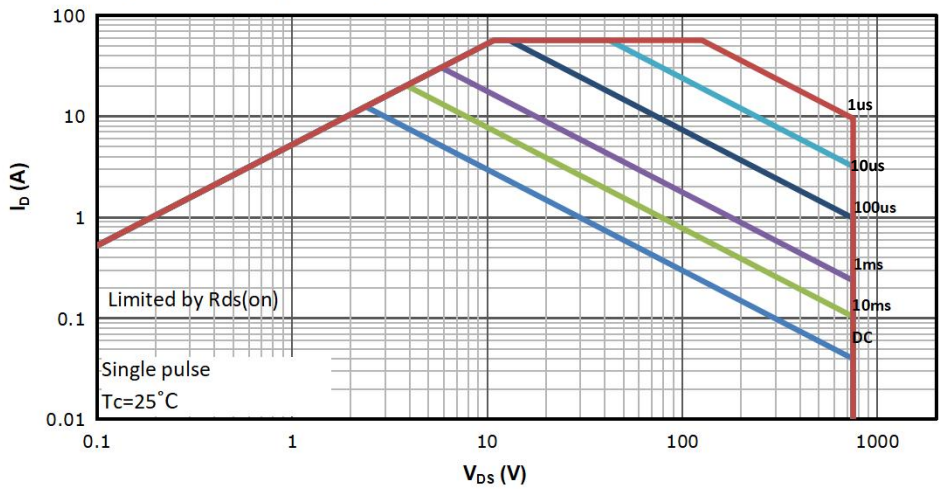
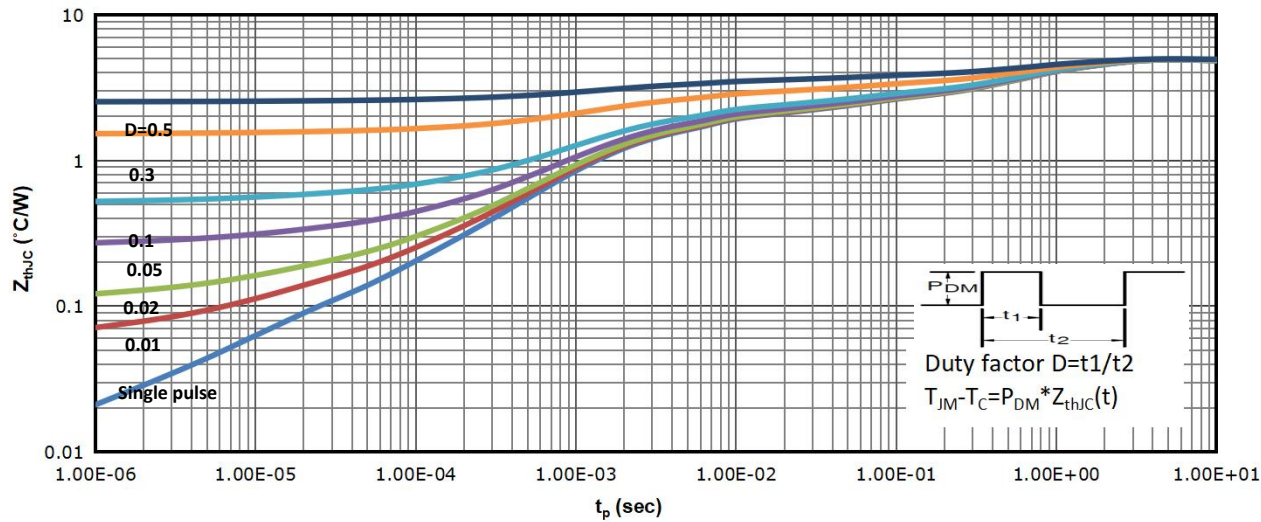
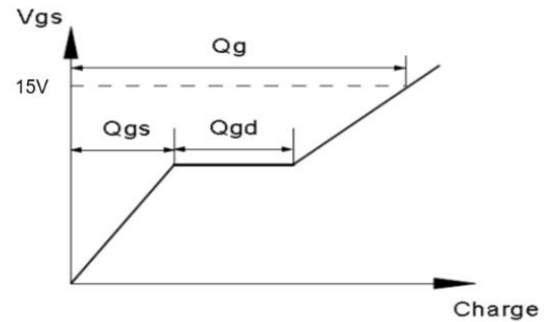
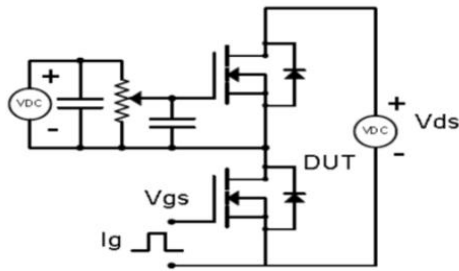


Fig 14: Max. Transient Thermal Impedance

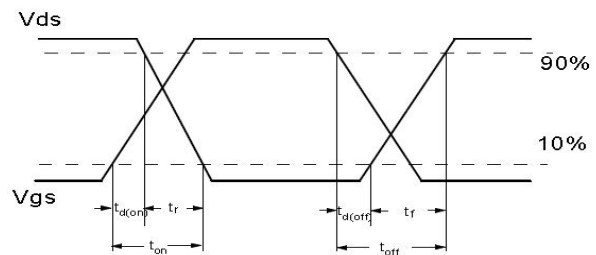
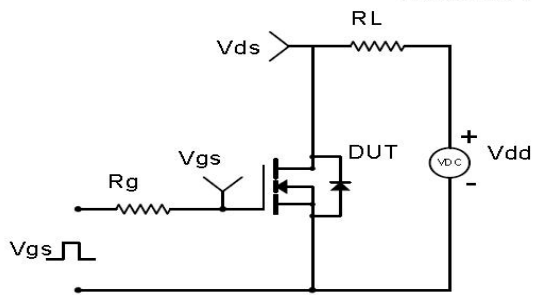


Test Circuit & Waveform

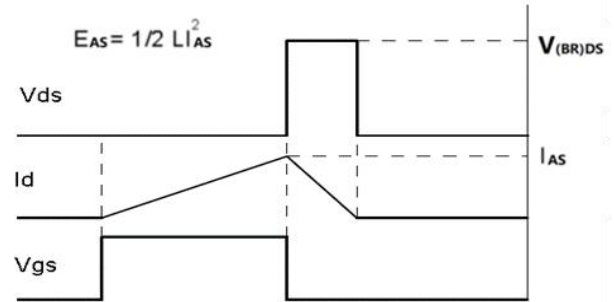
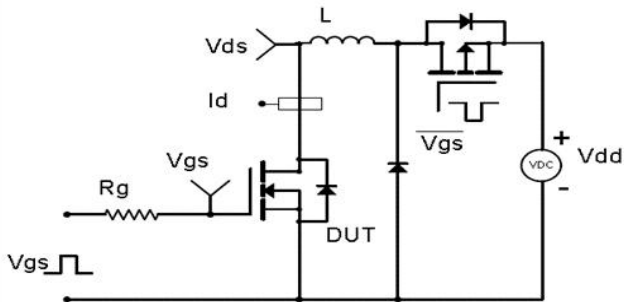
Gate Charge Test Circuit & Waveform



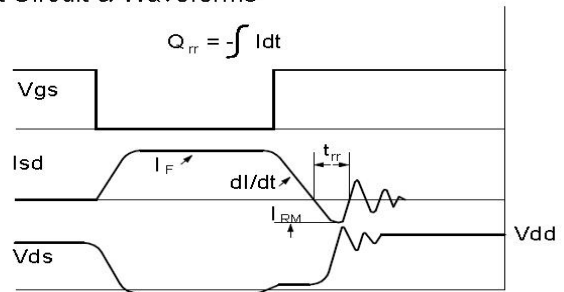
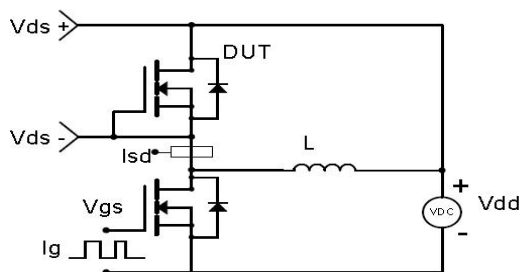
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



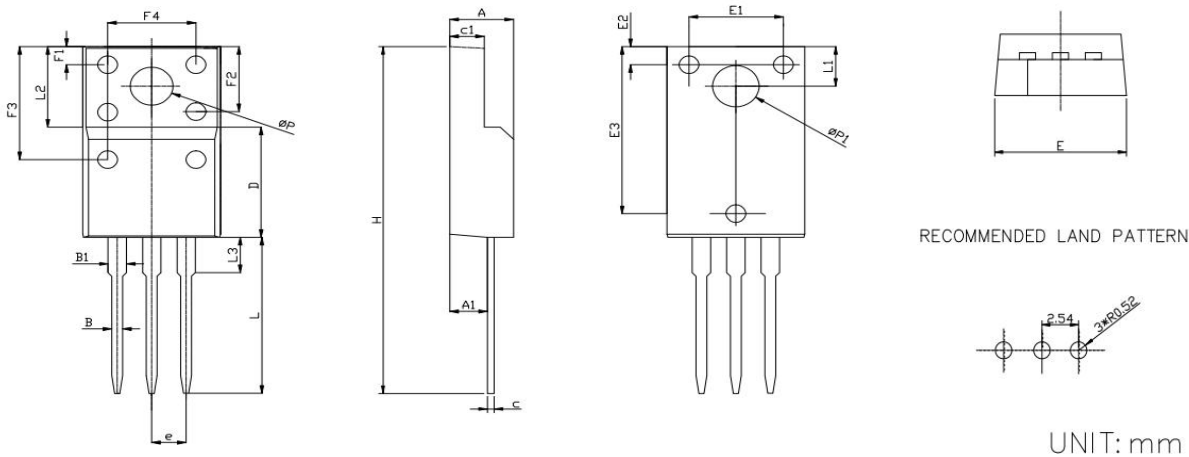
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Package Outline: TO-220TF-3L



SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.50	4.90	0.177	0.193
A1	2.63	2.89	0.104	0.114
B	0.75	0.90	0.030	0.035
B1	1.15	1.55	0.045	0.061
C	0.40	0.60	0.016	0.024
C1	2.34	2.74	0.092	0.108
D	8.87	9.47	0.349	0.373
e	2.54		0.100	
E	9.86	10.46	0.388	0.412
E1	6.86	7.06	0.270	0.278
E2	1.40	1.60	0.055	
E3	13.80	14.00	0.543	0.551
F1	1.40	1.60	0.055	
F2	5.15	5.65	0.203	0.222
F3	9.10	9.70	0.358	0.382
F4	6.70	7.30	0.264	0.287
H	28.50	29.50	1.122	1.161
L	12.58	13.38	0.495	0.527
L1	3.15	3.45	0.124	0.136
L2	6.70		0.264	
L3	2.63	3.23	0.104	0.127
φP	2.90	3.48	0.114	0.137
φP1	3.15	3.75	0.124	0.148

Disclaimer

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